

## MOSFET Silicon N-Channel MOS



### 1. Applications

Single-ended flyback or two-transistor forward topologies.  
PC power, PD Adaptor, LCD & PDP TV and LED lighting.

### 2. Features

Low drain-source on-resistance:  
DFN5x6  $R_{DS(ON)} = 3.3m\Omega$  (typ.)  
TO220&220F&263  $R_{DS(ON)} = 3.6m\Omega$  (typ.)  
Easy to control Gate switching  
Enhancement mode:  $V_{th} = 1.2$  to  $2.5$  V

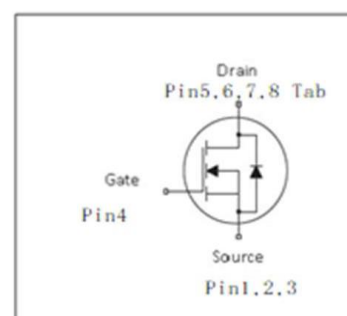
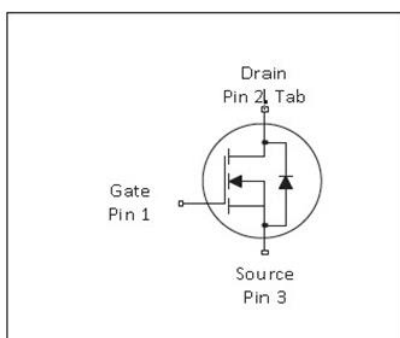
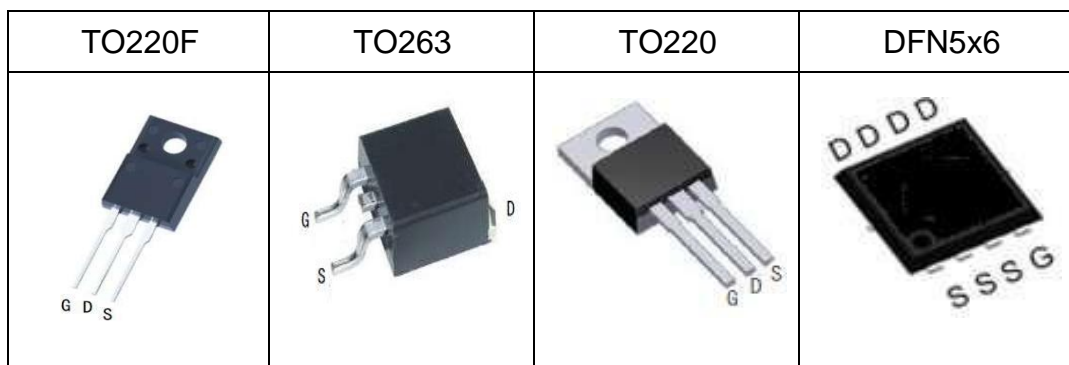


**Table 1 Key Performance Parameters**

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	100	V
$R_{DS(on),max}$ DFN5X6	3.6	m $\Omega$
$R_{DS(on),max}$ TO220	3.9	m $\Omega$
$Q_g,typ$	65	nC
$I_{D,pulse}$	437	A

### 3. Packaging and Internal Circuit

Part Name	Package	Marking
AUN036N10	DFN5X6	AUN036N10
AUP039N10	TO220	AUP039N10
AUA039N10	TO220F	AUA039N10
AUB039N10	TO263	AUB039N10



## 1 Maximum ratings

at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

**Table 2 Maximum ratings**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current <sup>1)</sup>	$I_D$		-	125	A	$T_C=25^\circ\text{C}$
Pulsed drain current <sup>2)</sup>	$I_{D,pulse}$	-	-	437	A	$T_C=25^\circ\text{C}$
Avalanche energy, single pulse	$E_{AS}$	-	-	306	mJ	$T_C=25^\circ\text{C}$ , $V_{DD}=50\text{V}$ , $I=35\text{A}$ , $L=0.1\text{mH}$ , $R_G=25\Omega$
Avalanche current, single pulse	$I_{AR}$	-	-	35	A	$T_C=25^\circ\text{C}$ , $V_{DD}=50\text{V}$ , $L=0.1\text{mH}$ , $R_G=25\Omega$
Gate source voltage (static)	$V_{GS}$	-20	-	20	V	static;
Power dissipation(TO220&263)	$P_{tot}$	-	-	151	W	$T_C=25^\circ\text{C}$
Power dissipation (TO220F)	$P_{tot}$	-	-	30	W	$T_C=25^\circ\text{C}$
Power dissipation (DFN5X6)	$P_{tot}$	-	-	75	W	$T_C=25^\circ\text{C}$
Storage temperature	$T_{stg}$	-55	-	150	$^\circ\text{C}$	
Operating junction temperature	$T_j$	-55	-	150	$^\circ\text{C}$	
Soldering Temperature Distance of 1.6mm from case for 10s	$T_L$			260	$^\circ\text{C}$	

<sup>1)</sup>Limited by  $T_{j,max}$ . Maximum Duty Cycle  $D = 0.50$

<sup>2)</sup>Pulse width  $t_p$  limited by  $T_{j,max}$

<sup>3)</sup>Identical low side and high side switch with identical  $R_G$

## 2 Thermal characteristics

**Table 3 Thermal characteristics (TO220F)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	$R_{thJC}$	-	-	4.2	°C/W	-
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	60	°C/W	device on PCB, minimal footprint

**Table Thermal characteristics (TO263&TO220)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	$R_{thJC}$	-	-	0.83	°C/W	-
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	62	°C/W	device on PCB, minimal footprint

**Table Thermal characteristics (DFN5x6)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	$R_{thJC}$	-	-	1.7	°C/W	-
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	50	°C/W	device on PCB, minimal footprint

### 3 Electrical characteristics

at  $T_j=25^{\circ}\text{C}$ , unless otherwise specified

**Table 4 Static characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	100	-	-	V	$V_{GS}=0V, I_D=250\mu A$
Gate threshold voltage	$V_{(GS)th}$	1.2	1.8	2.5	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Zero gate voltage drain current	$I_{DSS}$	-	-	1	$\mu A$	$V_{DS}=80V, V_{GS}=0V, T_j=25^{\circ}\text{C}$
Gate-source leakage current	$I_{GSS}$	-	-	$\pm 100$	nA	$V_{GS}=\pm 20V, V_{DS}=0V$
Drain-source on-state resistance DFN5x6	$R_{DS(on)}$	-	3.3	3.6	m $\Omega$	$V_{GS}=10V, I_D=20A, T_j=25^{\circ}\text{C}$
Drain-source on-state resistance TO220&220F&263	$R_{DS(on)}$	-	3.6	3.9	m $\Omega$	$V_{GS}=10V, I_D=20A, T_j=25^{\circ}\text{C}$
Gate resistance (Intrinsic)	$R_G$	-	0.6	-	$\Omega$	$f=1\text{MHz}$ , open drain

**Table 5 Dynamic characteristics(by calculating)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	$C_{iss}$	-	3562	-	PF	$V_{GS}=0V, V_{DS}=50V, f=1\text{MHz}$
Output capacitance	$C_{oss}$	-	865	-	PF	$V_{GS}=0V, V_{DS}=50V, f=1\text{MHz}$
Reverse transfer capacitance	$C_{rss}$	-	83	-	PF	$V_{GS}=0V, V_{DS}=50V, f=1\text{MHz}$
Turn-on delay time	$t_{d(on)}$	-	29	-	ns	$V_{DD}=50V, V_{GS}=10V, I_D=20A, R_G=10\Omega$
Rise time	$t_r$	-	55	-	ns	$V_{DD}=50V, V_{GS}=10V, I_D=20A, R_G=10\Omega$
Turn-off delay time	$t_{d(off)}$	-	69	-	ns	$V_{DD}=50V, V_{GS}=10V, I_D=20A, R_G=10\Omega$
Fall time	$t_f$	-	43	-	ns	$V_{DD}=50V, V_{GS}=10V, I_D=20A, R_G=10\Omega$

**Table 6 Gate charge characteristics(by calculating)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	$Q_{gs}$	-	15.5	-	nC	$V_{DD}=50V, I_D=20A, V_{GS}=0$ to 10V
Gate to drain charge	$Q_{gd}$	-	17.6	-	nC	$V_{DD}=50V, I_D=20A, V_{GS}=0$ to 10V
Gate charge total	$Q_g$	-	60.7	-	nC	$V_{DD}=50V, I_D=20A, V_{GS}=0$ to 10V

**Table 7 Reverse diode characteristics(by calculating)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	$V_{SD}$	-	0.7	-	V	$V_{GS}=0V, I_F=1A, T_J=25^{\circ}C$
Reverse recovery time	$t_{rr}$	-	45	-	ns	$V_R=30V, I_F=20A, di/dt=300A/\mu s$
Reverse recovery charge	$Q_{rr}$	-	212	-	nC	$V_R=30V, I_F=20A, di/dt=300A/\mu s$
Peak reverse recovery current	$I_{rrm}$	-	8.4	-	A	$V_R=30V, I_F=20A, di/dt=300A/\mu s$

## 4 Electrical characteristics diagram

Diagram 1: Typ. Output characteristics

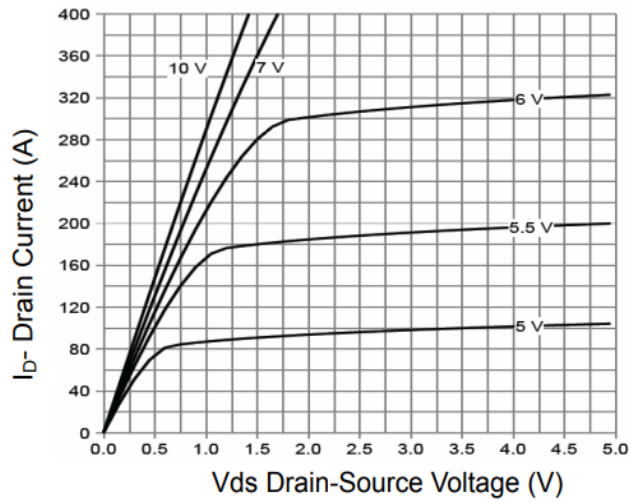


Diagram 2: Typ. Transfer characteristics

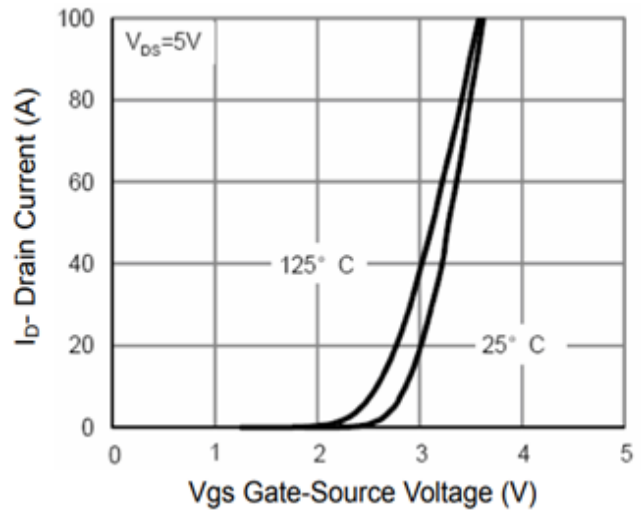


Diagram 3: Typ. Rds(on) vs. Drain Current

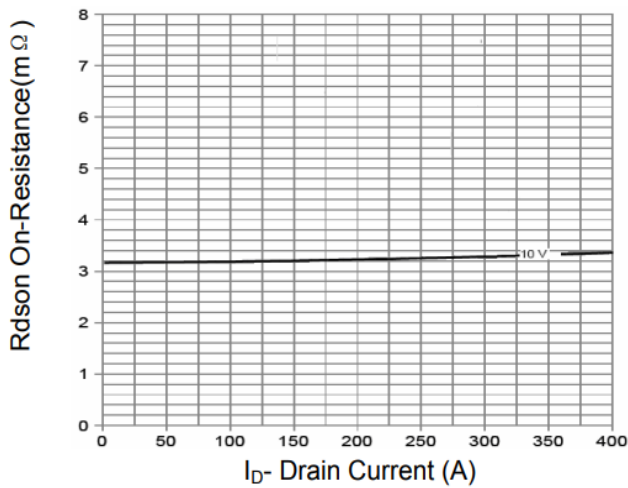


Diagram 4: Typ. Rds(on) – Junction Temperature

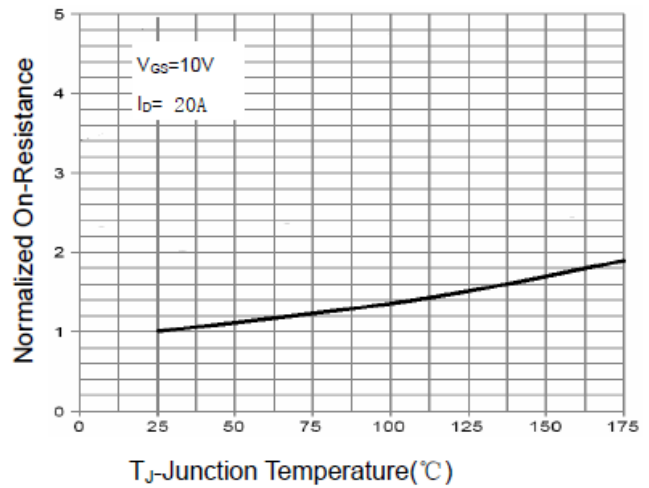


Diagram 5: Typ. Body-Diode Characteristics

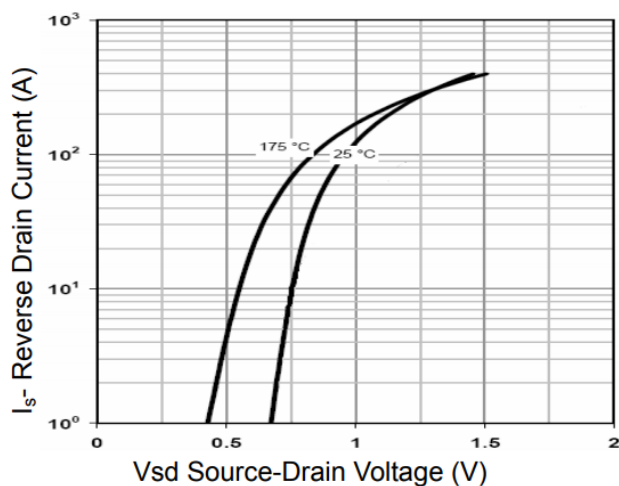


Diagram 6: Typ. Capacitance vs. Vds

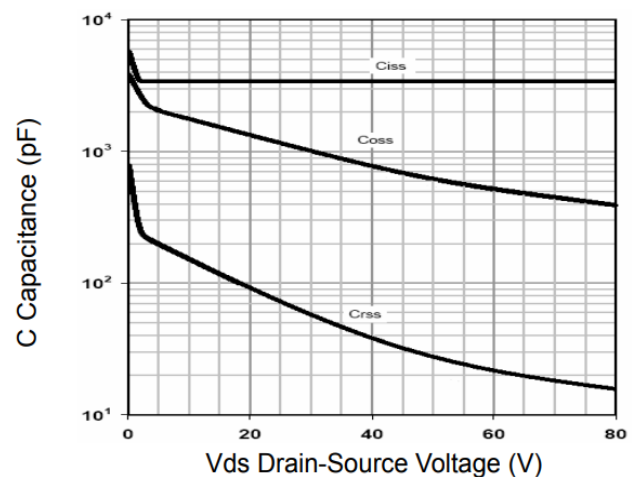


Diagram 7: Typ. Power Dissipation

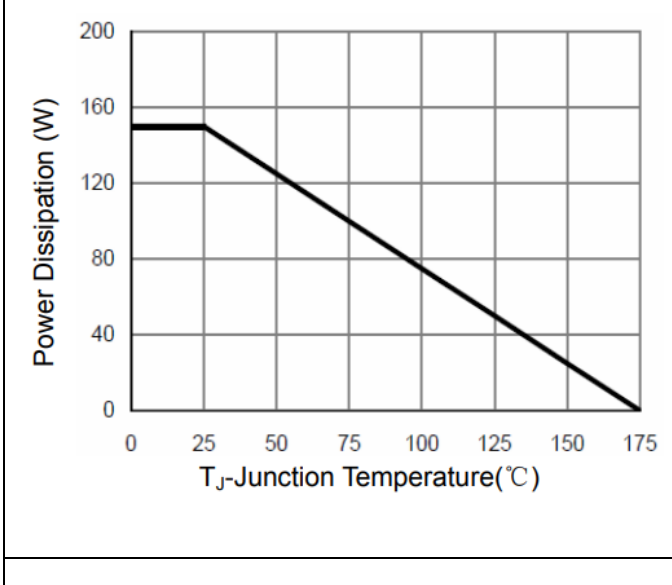


Diagram 8: Typ. Drain Current De-rating

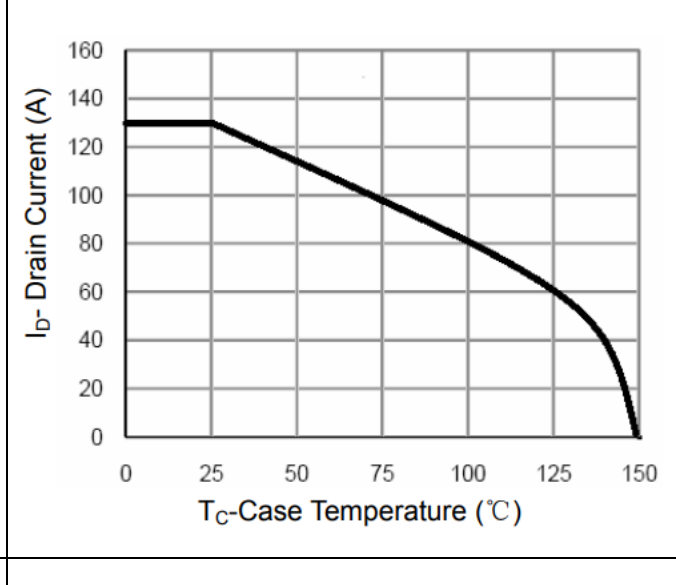


Diagram 9: Typ. Gate charge

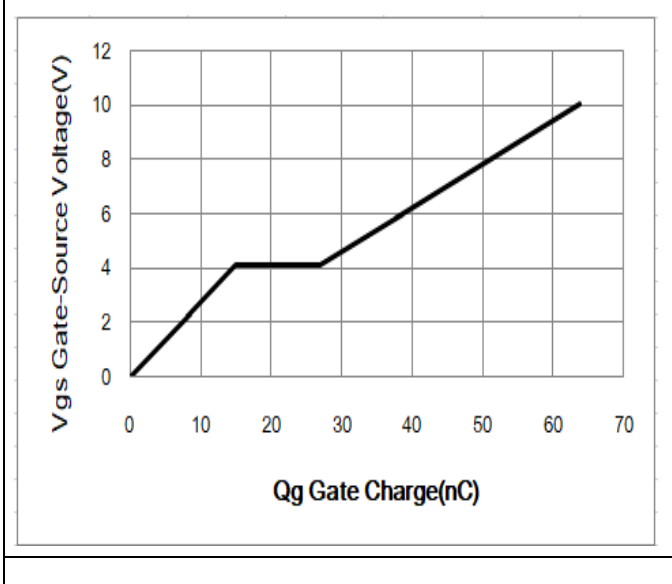


Diagram 10: Typ. Maximum Safe Operating Area

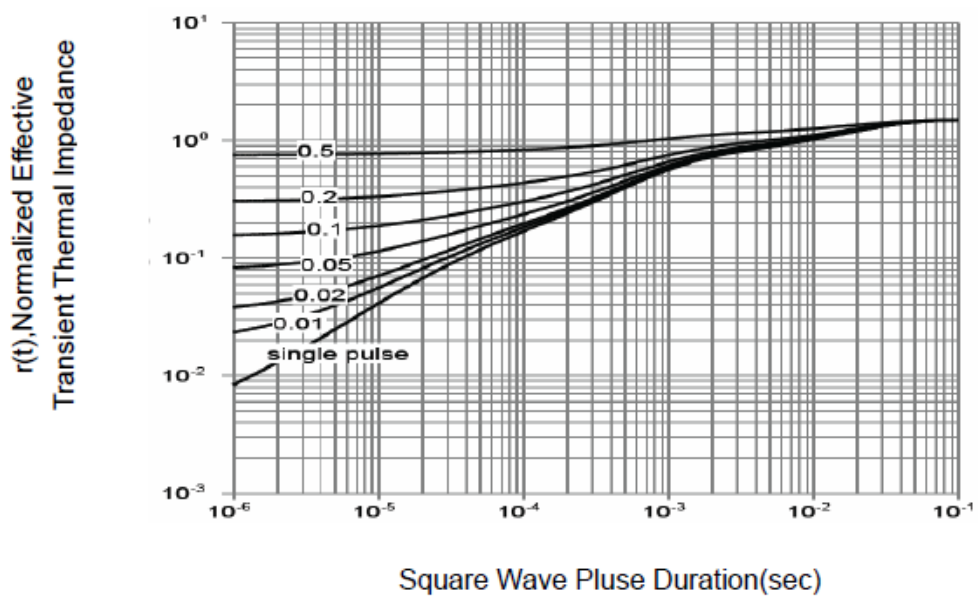
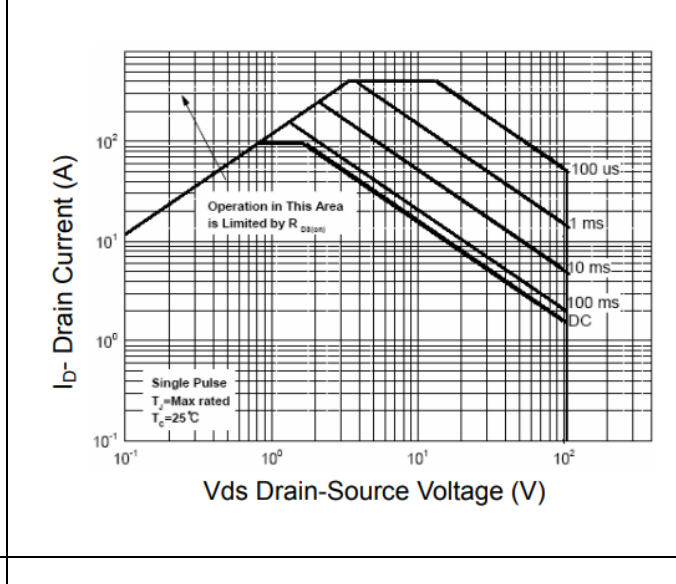


Figure 11 Normalized Maximum Transient Thermal Impedance

## 5 Test Circuits

Table 8 Diode characteristics

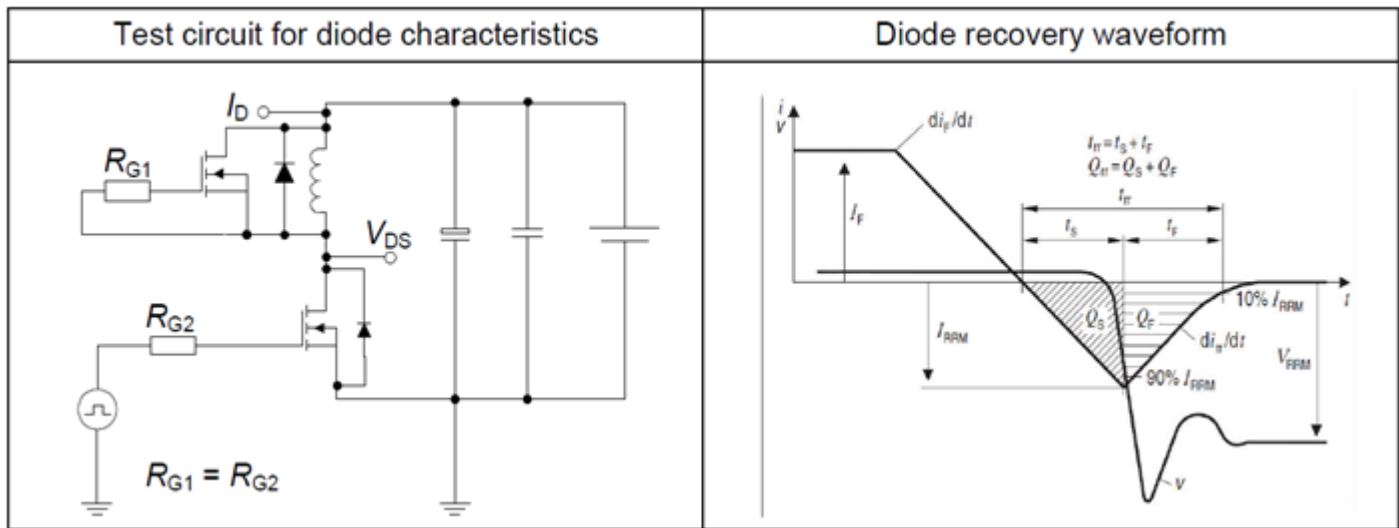


Table 9 Switching times

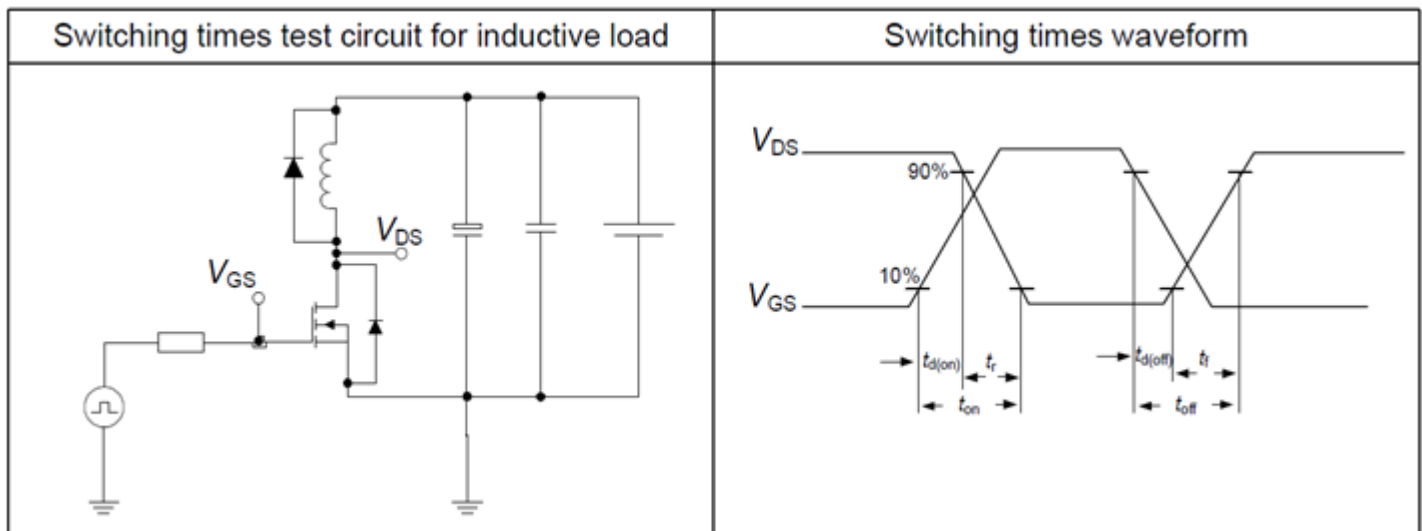
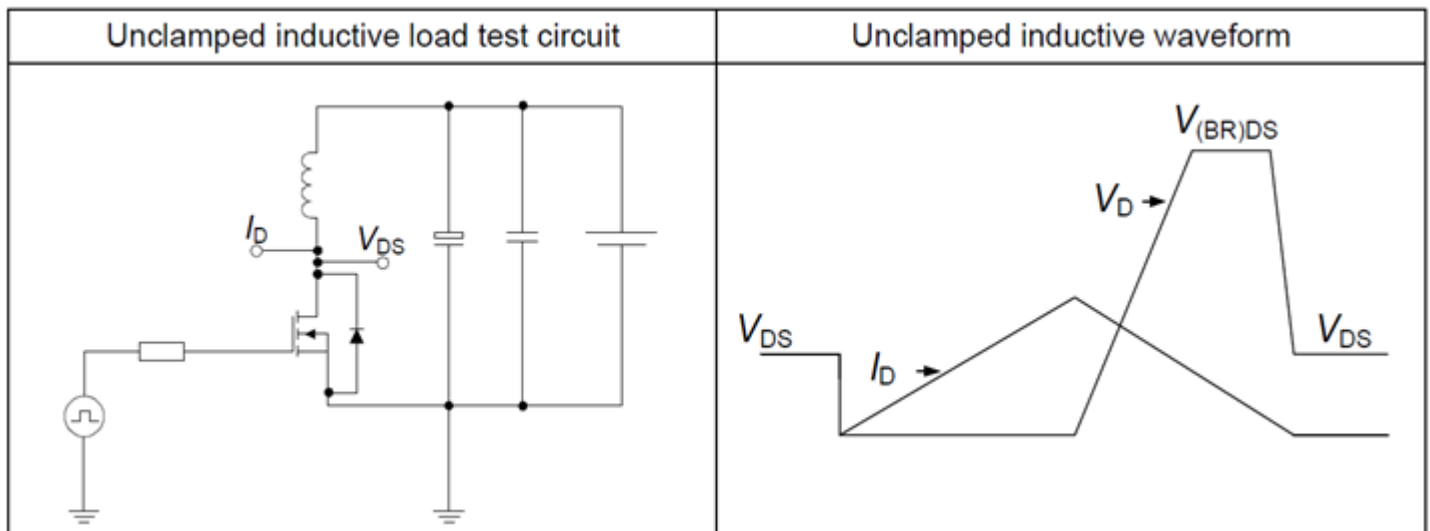
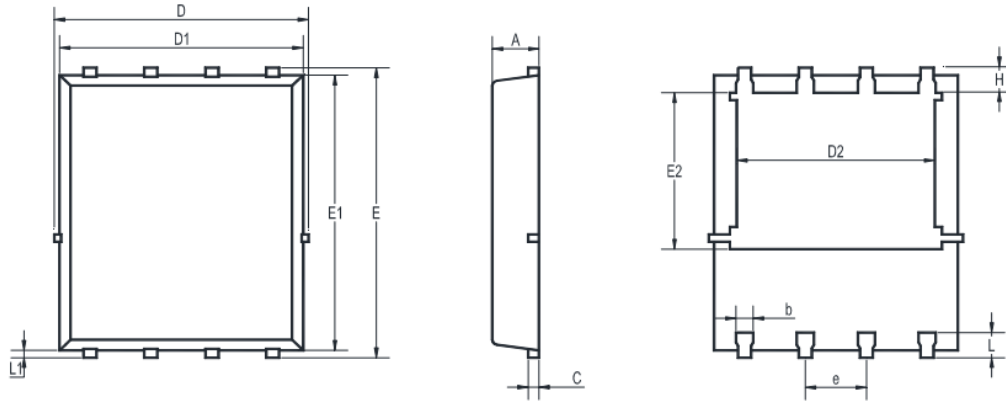


Table 10 Unclamped inductive load



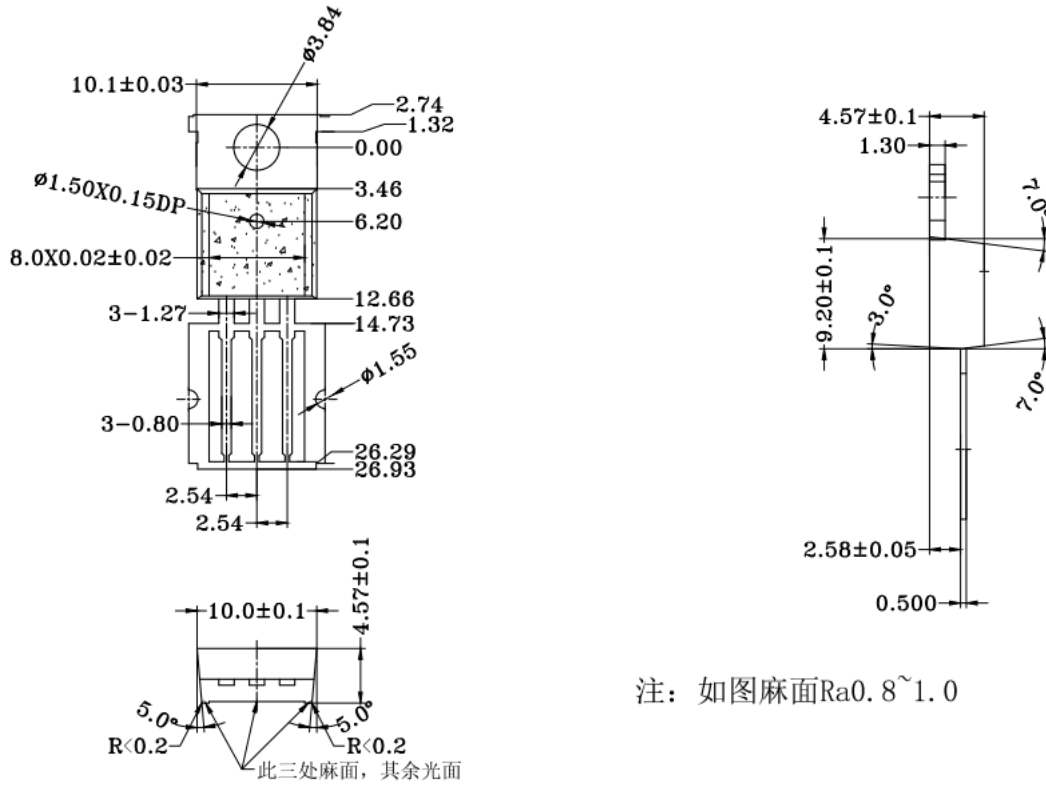


## 6 Package Outlines



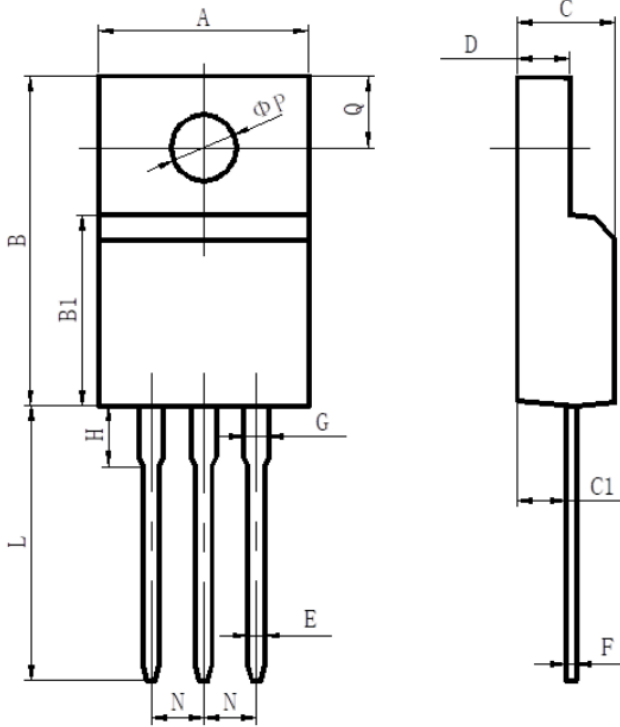
UNIT	A	b	C	D	D1	D2	E	E1	E2	e	L	L1	H
mm	1.12	0.51	0.34	5.26	5.1	4.5	6.25	6	3.66	1.37	0.71	0.2	0.71
	0.9	0.33	0.11	4.7	4.7	3.56	5.75	5.6	3.18	1.17	0.35	0.06	0.35

Figure1: Outline PG-DFN5X6(HC)



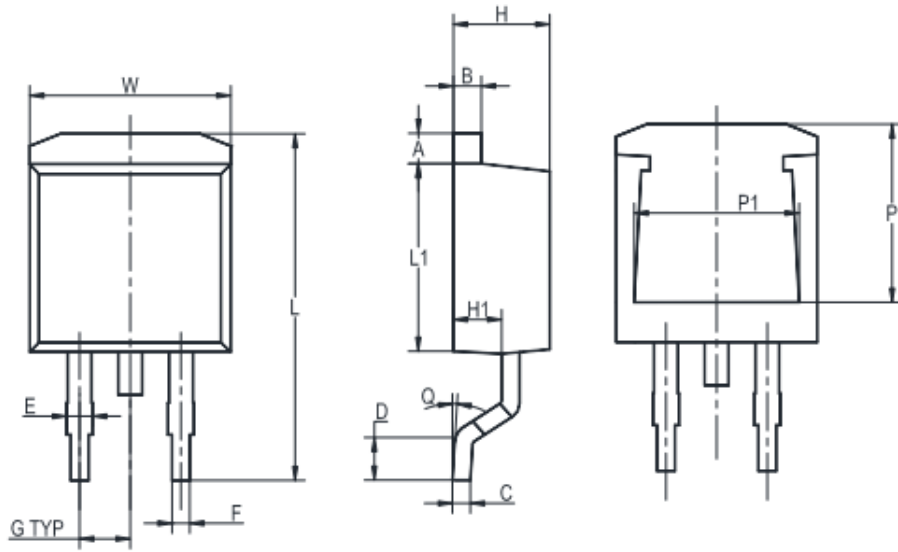
注：如图麻面Ra0.8~1.0

Figure2: Outline PG-T0220(HT)



项目	规范(mm)	
	MIN	MAX
A	9.70	10.30
B	15.50	16.10
B1	8.99	9.39
C	4.40	4.80
C1	2.15	2.55
D	2.50	2.90
E	0.70	0.90
F	0.40	0.60
G	1.12	1.42
H	3.40	3.80
L	12.6	13.6
N	2.34	2.74
Q	3.15	3.55
$\Phi P$	3.00	3.30

Figure3: Outline PG-TO220F(HT)



UNIT	A	B	C	D	E	F	G	W	H	H1	L	L1	Q	P	P1
mm	1.5	1.5	0.5	2.60	1.6	0.94	2.54	10.5	4.8	2.9	16.5	8.7	8°	7.6	8.2
	1.1	1.1	0.3	2.15	1.1	0.68	TYP	9.6	4.4	2.5	14.5	8.2	MAX	7.1	7.4

Figure4: Outline PG-TO263(HC&LM)

**Revision History**

Revision	Date	Subjects (major changes since last revision)
1.0	2022-08-03	Preliminary version
1.1	2022-09-14	Updated Vth limit
1.2	2022-11-16	Added package TO220
1.3	2023-02-06	Updated diagram2 transfer characteristics
1.4	2023-06-06	Added TO220F&263 package